# **BLP05H6150XR**

# **Power LDMOS transistor**

**AMPLEON** 

Rev. 3 — 8 January 2016

Product data sheet

### 1. Product profile

### 1.1 General description

A 150 W extremely rugged LDMOS power transistor for broadcast and industrial applications in the HF to 600 MHz band.

Table 1. Application information

Test signal	f	V <sub>DS</sub>	PL	Gp	$\eta_{D}$	ACPR
	(MHz)	(V)	(W)	(dB)	(%)	(dBc)
pulsed RF	108	50	150	27	75	-
CW	1.8 to 30	50	100	29	60	-
	135	50	150	26	73	-
	174 to 230	50	150	22	67	-
DVB-T	174 to 230	50	25	23	29	-36

#### 1.2 Features and benefits

- Easy power control
- Integrated double sided ESD protection
- Excellent ruggedness
- High efficiency
- Excellent thermal stability
- Designed for broadband operation (HF to 600 MHz)
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

### 1.3 Applications

- Industrial, scientific and medical applications
- Broadcast transmitter applications

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	gate 2	4 0	,
2	gate 1	4 3	
3	drain 1		
4	drain 2	pin 1 index	. — 3
5	source	[1]	2 1
		1 2	3
			aaa-003574

[1] Connected to flange.

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BLP05H6150XR	HSOP4F	plastic, heatsink small outline package; 4 leads(flat)	SOT1223-2

## 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage		-	135	V
$V_{GS}$	gate-source voltage		-6	+11	V
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature	[1]	-	225	°C

<sup>[1]</sup> Continuous use at maximum temperature will affect the reliability, for details refer to the on-line MTF calculator.

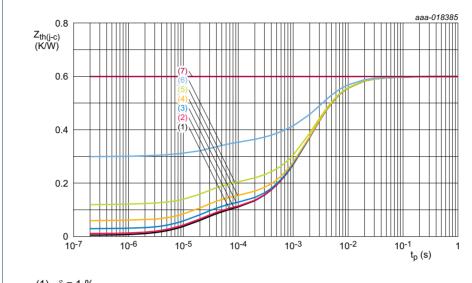
### 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Тур	Unit
R <sub>th(j-c)</sub>	thermal resistance from junction to case	T <sub>j</sub> = 125 °C	1][2]	0.6	K/W
Z <sub>th(j-c)</sub>	transient thermal impedance from junction to case	$T_j$ = 150 °C; $t_p$ = 100 μs; $δ$ = 20 %	[3]	0.21	K/W

- [1]  $T_j$  is the junction temperature.
- [2]  $R_{th(j-c)}$  is measured under RF conditions.
- [3] See Figure 1.

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- (1)  $\delta = 1 \%$
- (2)  $\delta = 2 \%$
- (3)  $\delta = 5 \%$
- (4)  $\delta = 10 \%$
- (5)  $\delta = 20 \%$
- (6)  $\delta = 50 \%$
- (7)  $\delta = 100 \% (DC)$

Transient thermal impedance from junction to case as a function of pulse Fig 1. duration

#### **Characteristics** 6.

Table 6. **DC** characteristics

 $T_i$  = 25 °C; per section unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 0.5 \text{ mA}$	135	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 50 mA	1.25	1.8	2.25	V
$V_{GSq}$	gate-source quiescent voltage	$V_{DS} = 50 \text{ V}; I_{D} = 20 \text{ mA}$	-	1.7	-	V
I <sub>DSS</sub>	drain leakage current	$V_{GS} = 0 \text{ V}; V_{DS} = 50 \text{ V}$	-	-	1.4	μА
I <sub>DSX</sub>	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $V_{DS} = 10 \text{ V}$	-	7.2	-	Α
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 11 V; V <sub>DS</sub> = 0 V	-	-	140	nA
R <sub>DS(on)</sub>	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $I_D = 1.75 \text{ A}$	-	0.8	-	Ω

Table 7. AC characteristics

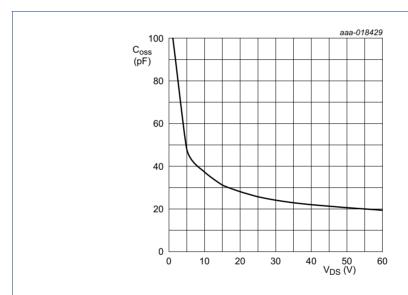
 $T_i$  = 25 °C; per section unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
C <sub>rs</sub>	feedback capacitance	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V; f = 1 MHz	-	0.5	-	pF
C <sub>iss</sub>	input capacitance	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 50 V; f = 1 MHz	-	60	-	pF
C <sub>oss</sub>	output capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 50 \text{ V}; f = 1 \text{ MHz}$	-	21	-	pF

#### Table 8. RF characteristics

Test signal: pulsed RF;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %; f = 108 MHz; RF performance at  $V_{DS}$  = 50 V;  $I_{Dq}$  = 100 mA;  $T_{case}$  = 25  $^{\circ}$ C; unless otherwise specified; in a class-AB production test circuit.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Gp	power gain	P <sub>L</sub> = 150 W	25.5	27	-	dB
RLin	input return loss	P <sub>L</sub> = 150 W	-	-8	-	dB
$\eta_{D}$	drain efficiency	P <sub>L</sub> = 150 W	73	75	-	%



 $V_{GS} = 0 V$ ; f = 1 MHz.

Fig 2. Output capacitance as a function of drain-source voltage; typical values per section

### 7. Test information

### 7.1 Ruggedness in class-AB operation

The BLP05H6150XR is capable of withstanding a load mismatch corresponding to VSWR > 65 : 1 through all phases under the following conditions:  $V_{DS}$  = 50 V;  $I_{Dq}$  = 40 mA;  $P_{L}$  = 150 W pulsed; f = 108 MHz.

### 7.2 Impedance information

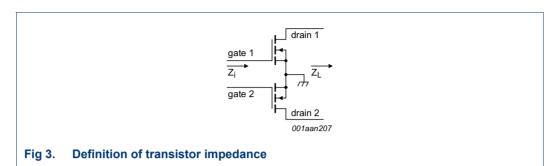


Table 9. Typical push-pull impedance

Simulated  $Z_i$  and  $Z_L$  device impedance; impedance info at  $V_{DS} = 50 \text{ V}$  and  $P_L = 150 \text{ W}$ .

f	Z <sub>i</sub>	$Z_L$
(MHz)	(Ω)	(Ω)
108	32 – j99	25 + j6.0

### 7.3 UIS avalanche energy

Table 10. Typical avalanche data per section

 $T_{amb}$  = 25 °C; typical test data; test jig without water cooling.

I <sub>AS</sub>	E <sub>AS</sub>
(A)	(J)
4	0.38
5	0.26
6	0.18

For information see application note AN10273.

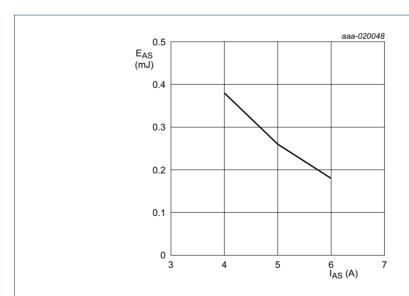
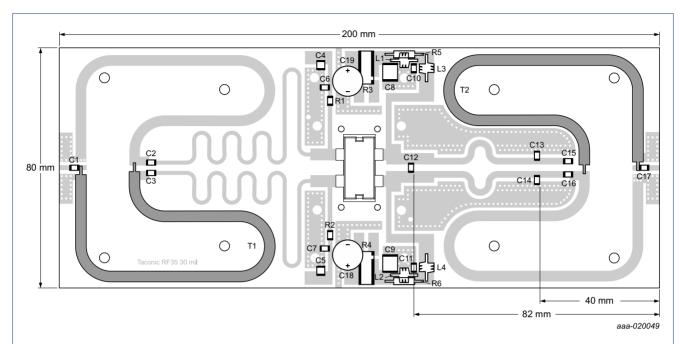


Fig 4. Non-repetitive avalanche energy as a function of single pulse avalanche current; typical values

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### 7.4 Test circuit



Printed-Circuit Board (PCB): RF-35;  $\epsilon_r$  = 3.5 F/m; thickness = 0.765 mm; thickness copper plating = 35  $\mu$ m. See <u>Table 11</u> for a list of components.

Fig 5. Component layout for class-AB production test circuit

Table 11. List of components

For test circuit see Figure 5.

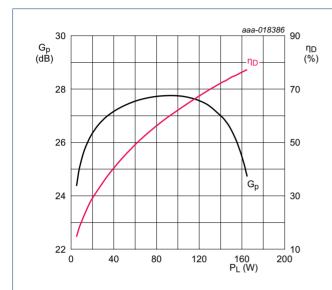
Component	Description	Value		Remarks
C1	multilayer ceramic chip capacitor	68 pF	[1]	
C2, C3	multilayer ceramic chip capacitor	220 pF	[1]	
C4, C5	multilayer ceramic chip capacitor	4.7 μF, 50 V		Kemet: C1210X475K5RAC-T4
C6, C7	multilayer ceramic chip capacitor	750 pF	[1]	
C8, C9	multilayer ceramic chip capacitor	4.7 μF, 100 V		TDK: C5750X7R2A475KT
C10, C11	multilayer ceramic chip capacitor	750 pF	[1]	
C12	multilayer ceramic chip capacitor	10 pF	[1]	
C13, C14	multilayer ceramic chip capacitor	43 pF	[1]	
C15, C16	multilayer ceramic chip capacitor	390 pF	[1]	
C17	multilayer ceramic chip capacitor	47 pF	[1]	
C18,C19	electrolytic capacitor	2200 μF, 64 V		
L1, L2	wire inductor	5 turns, D = 3 mm, 1 mm copper wire		
L3, L4	wire inductor	6 turns, D = 3 mm, 1 mm copper wire		
R1, R2	resistor	4.7 kΩ		SMD 1206
R3, R4	shunt resistor	0.01 Ω		Ohmite: FC4L110R010FER
R5, R6	metal film resistor	10 Ω, 0.6 W		
T1, T2	semi rigid coax	50 Ω, length = 160 mm		EZ Form: EZ-141-AL-TP-M17

<sup>[1]</sup> American Technical Ceramics type 100B or capacitor of same quality.

### 7.5 Graphical data

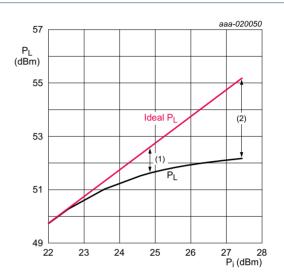
The following figures are measured in a class-AB production test circuit.

### 7.5.1 1-Tone CW pulsed



 $V_{DS}$  = 50 V;  $I_{Dq}$  = 40 mA; f = 108 MHz;  $t_p$  = 100  $\mu s$ ;  $\delta$  = 20 %.

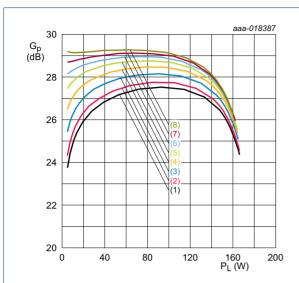
Fig 6. Power gain and drain efficiency as function of output power; typical values



 $V_{DS}$  = 50 V;  $I_{Dq}$  = 40 mA; f = 108 MHz;  $t_p$  = 100  $\mu s;$   $\delta$  = 20 %.

- (1)  $P_{L(1dB)} = 51.6 \text{ dBm } (146 \text{ W})$
- (2)  $P_{L(3dB)} = 52.2 \text{ dBm } (165 \text{ W})$

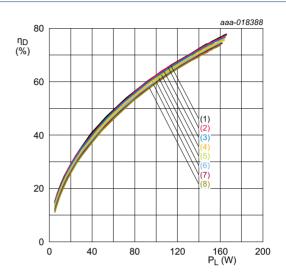
Fig 7. Output power as a function of input power; typical values



 $V_{DS}$  = 50 V; f = 108 MHz;  $t_p$  = 100  $\mu s;$   $\delta$  = 20 %.

- (1)  $I_{Dq} = 20 \text{ mA}$
- (2)  $I_{Dq} = 40 \text{ mA}$
- (3)  $I_{Dq} = 100 \text{ mA}$
- (4)  $I_{Dq} = 200 \text{ mA}$
- (5)  $I_{Dq} = 300 \text{ mA}$
- (6)  $I_{Dq} = 400 \text{ mA}$
- (7)  $I_{Dq} = 500 \text{ mA}$
- (8)  $I_{Dq} = 600 \text{ mA}$

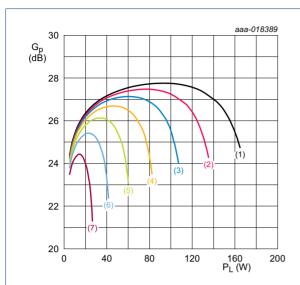
Fig 8. Power gain as a function of output power; typical values



 $V_{DS}$  = 50 V; f = 108 MHz;  $t_p$  = 100  $\mu s;$   $\delta$  = 20 %.

- (1)  $I_{Dq} = 20 \text{ mA}$
- (2)  $I_{Dq} = 40 \text{ mA}$
- (3)  $I_{Dq} = 100 \text{ mA}$
- (4)  $I_{Dq} = 200 \text{ mA}$
- (5)  $I_{Dq} = 300 \text{ mA}$
- (6)  $I_{Dq} = 400 \text{ mA}$
- (7)  $I_{Dq} = 500 \text{ mA}$
- (8)  $I_{Dq} = 600 \text{ mA}$

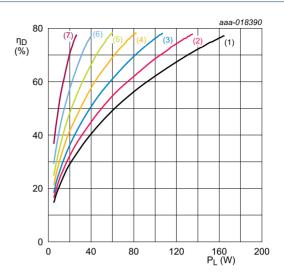
Fig 9. Drain efficiency as a function of output power; typical values



 $I_{Dq}$  = 40 mA; f = 108 MHz;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %.

- (1)  $V_{DS} = 50 \text{ V}$
- (2)  $V_{DS} = 45 \text{ V}$
- (3)  $V_{DS} = 40 \text{ V}$
- (4)  $V_{DS} = 35 \text{ V}$
- (5)  $V_{DS} = 30 \text{ V}$
- (6)  $V_{DS} = 25 \text{ V}$
- (7)  $V_{DS} = 20 \text{ V}$

Fig 10. Power gain as a function of output power; typical values



 $I_{Dq}$  = 40 mA; f = 108 MHz;  $t_p$  = 100  $\mu$ s;  $\delta$  = 20 %.

- (1)  $V_{DS} = 50 \text{ V}$
- (2)  $V_{DS} = 45 \text{ V}$
- (3)  $V_{DS} = 40 \text{ V}$
- (4)  $V_{DS} = 35 V$
- (5)  $V_{DS} = 30 \text{ V}$
- (6)  $V_{DS} = 25 \text{ V}$
- (7)  $V_{DS} = 20 \text{ V}$

Fig 11. Drain efficiency as a function of output power; typical values

### 8. Package outline

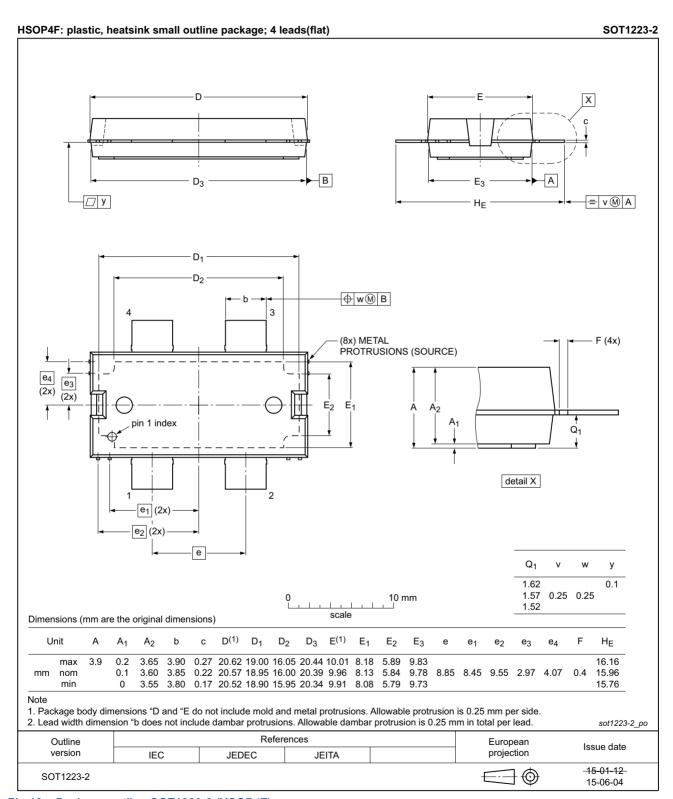


Fig 12. Package outline SOT1223-2 (HSOP4F)

## 9. Handling information

#### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

### 10. Abbreviations

Table 12. Abbreviations

Acronym	Description	
CW	Continuous Wave	
DVB-T	Digital Video Broadcast - Terrestrial	
ESD	ElectroStatic Discharge	
HF	High Frequency	
LDMOS	Laterally Diffused Metal-Oxide Semiconductor	
MTF	Median Time to Failure	
SMD	Surface Mounted Device	
UIS	Unclamped Inductive Switching	
VSWR	Voltage Standing-Wave Ratio	

## 11. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes		
BLP05H6150XR v.3	20160108	Product data sheet	-	BLP05H6150XR#2		
Modifications	<u>Table 1 on page 1</u> : table updated					
	Section 1.2 on page 1: table updated					
	<u>Table 5 on page 2</u> : table updated					
	• Figure 1 on page 3: figure added					
	• <u>Table 8 on page 4</u> : table updated					
	• Figure 2 on page 4: figure added					
	• Figure 3 on page 5: figure updated					
	<ul> <li>Table 9 on page 5: table updated</li> <li>Table 10 on page 5: table updated</li> <li>Figure 4 on page 5: figure added</li> <li>Section 7.4 on page 6: section added</li> </ul>					
	Section 7.5	• Section 7.5 on page 7: section added				
BLP05H6150XR#2	20150901	Objective data sheet	-	BLP05H6150XR v.1		
BLP05H6150XR v.1	20150518	Objective data sheet	-	-		

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#### 12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions"
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# **BLP05H6150XR**

### **Power LDMOS transistor**

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